

Vision and Development of DAS

- a LS-DYNA based Die System Analysis

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Summary:

DYNAFORM has been known as a LS-DYNA based sheet metal forming simulation solution package. With additional development to support various manufacturing requirements, ETA has delivered a first version of DYNAFORM-DSA Module, it is defined as "A LS-DYNA based Die System Analysis solution package."

In the DSA Module, it covers the die structure strength and durability study, scrap shedding and removal prediction, support sheet metal transferring and handling design. All the simulations are done with both implicit and explicit solvers of LS-DYNA.

The presentation will cover the newly developed methodology, software product and production examples.